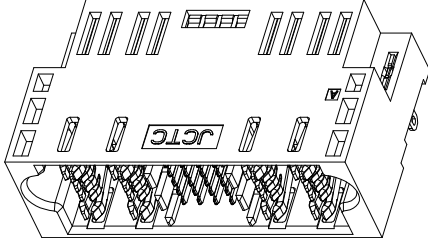
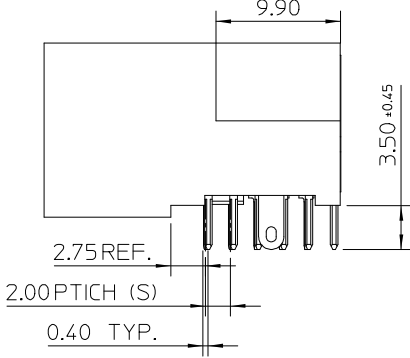
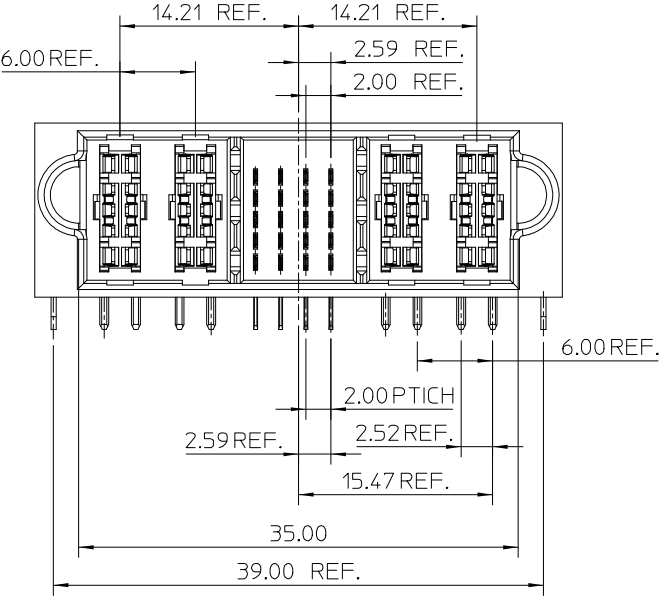
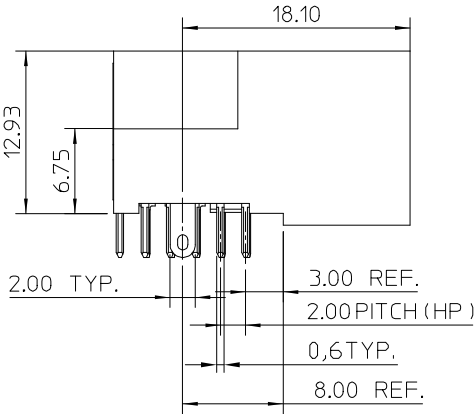
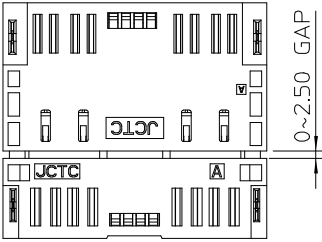
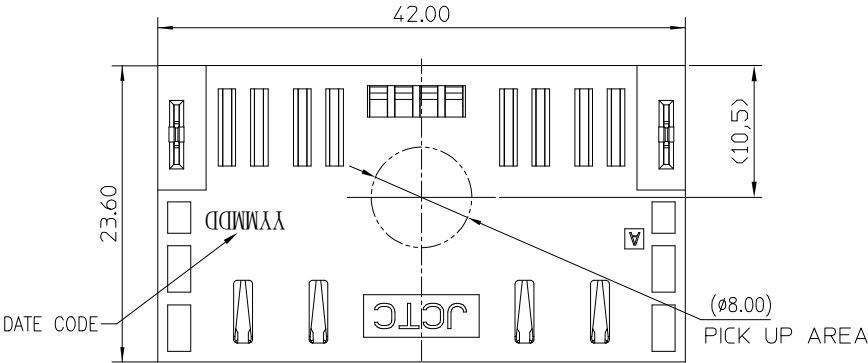
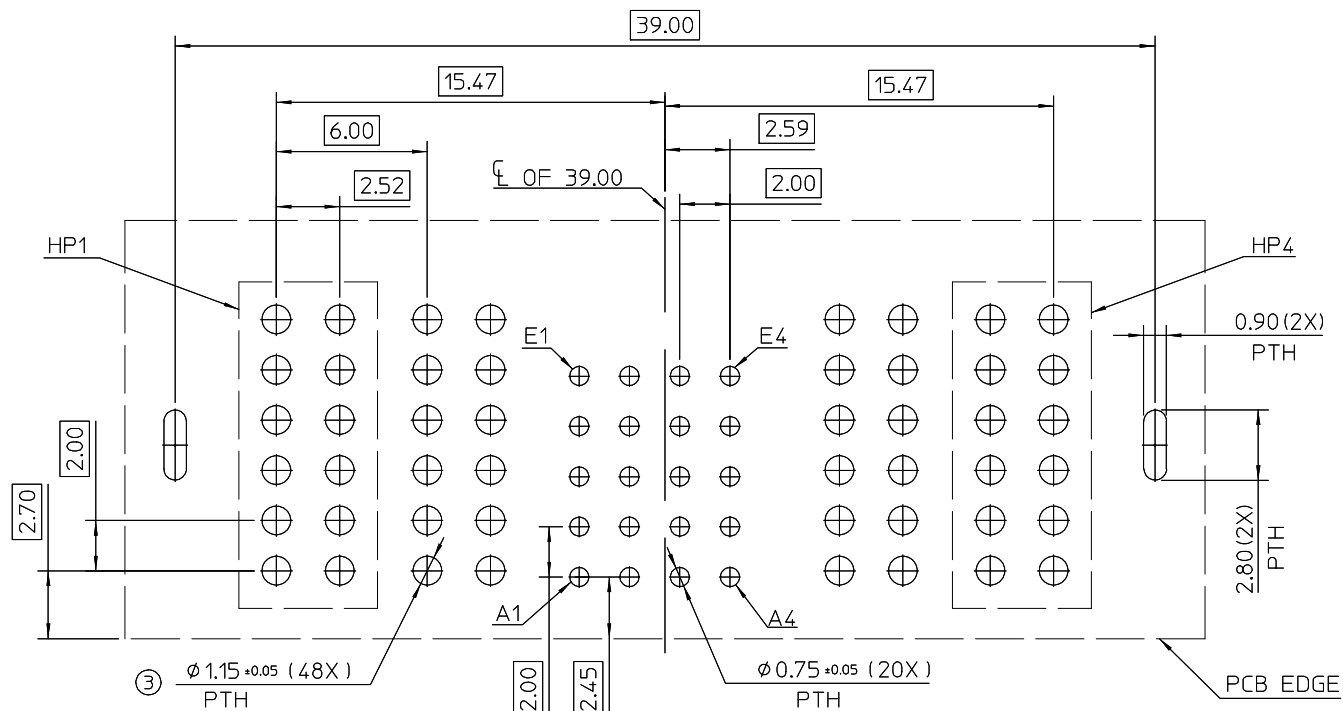


RoHS 2.0+HF



ROWS	HIGH POWER	SIGNAL				HIGH POWER
		1	2	3	4	
5	HP1 HP2	E	E	E	E	HP3 HP4
4		D	D	D	D	
3		C	C	C	C	
2		B	B	B	B	
1		A	A	A	A	

REV.	REVISION RECORD	DATE		GENERAL TOLERANCES		SCALE 1:1	NAME	DATE	PART NO.	DWG NO.				
X0	FIRST RELEASE	2026.01.06		LINEAR	ANGLES	APPROVED	Jackie Tan	2026.04.22	19-01-000016	ENDE05				
X1	Update the structure according	2026.04.22		0.0±0.25	X° REF±6°	DESIGNER	Daniel Dong	2026.04.22	TITLE BOARD TO BOARD CONN 6.0&2.0&2P+20S+2P CIRCUTIS REC R/A DIP TYPE					
				UNIT: MM	0.00±0.15	X° ±3°	DRAWN	Hu.CH						
			SIZE: A4	0.000±0.08	X° X' ±2°						REV	X1	SHEET	1/3



RECOMMENDED PCB BOARD LAYOUT PCB THICKNESS: 3.00MM
(DIMENSION TOLERANCE IS ±0.05MM) (TOP VIEW)

Specifications:

1. Material And Finish:

- Insulator: Thermoplastic UL94 V-0 Black.
- Terminal: Copper Alloy.
- High Power: Gold Plated on Contact Area 30u" Min.
- Signal: Gold Plated 5u" Min. on Contact Area
Matte Tin Plated 100u" Min. on Solder Tail,
Nickel Under Plated 50u" Min. Overall

2.Environmental Specification:

- Operating Temperature: $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$.

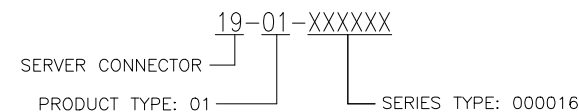
3. Electrical Specification:

- Insulation Resistance:
High Power: 1000M Ohms Min. At 500V DC For 60s.
Signal: 500M Ohms Min. At 500V DC For 60s.
- Withstanding Voltage:
High Power: 2500V Min. DC For 60 Seconds.
Signal: 1000V Min. DC For 60 Seconds.
- Current Rating: High Power 200A; Signal 1.0A

4.This Part is Design for Pip Soldering Process,
Peak Soldering Temperature: 250°C, 10~20S.

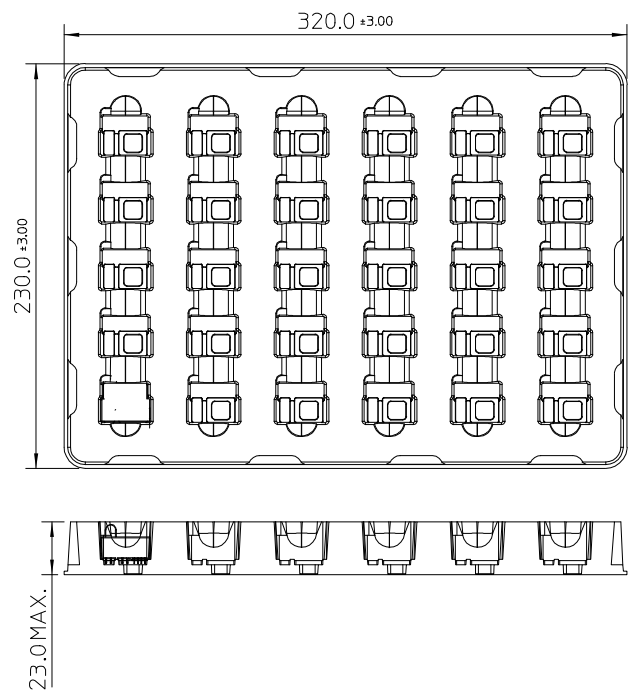
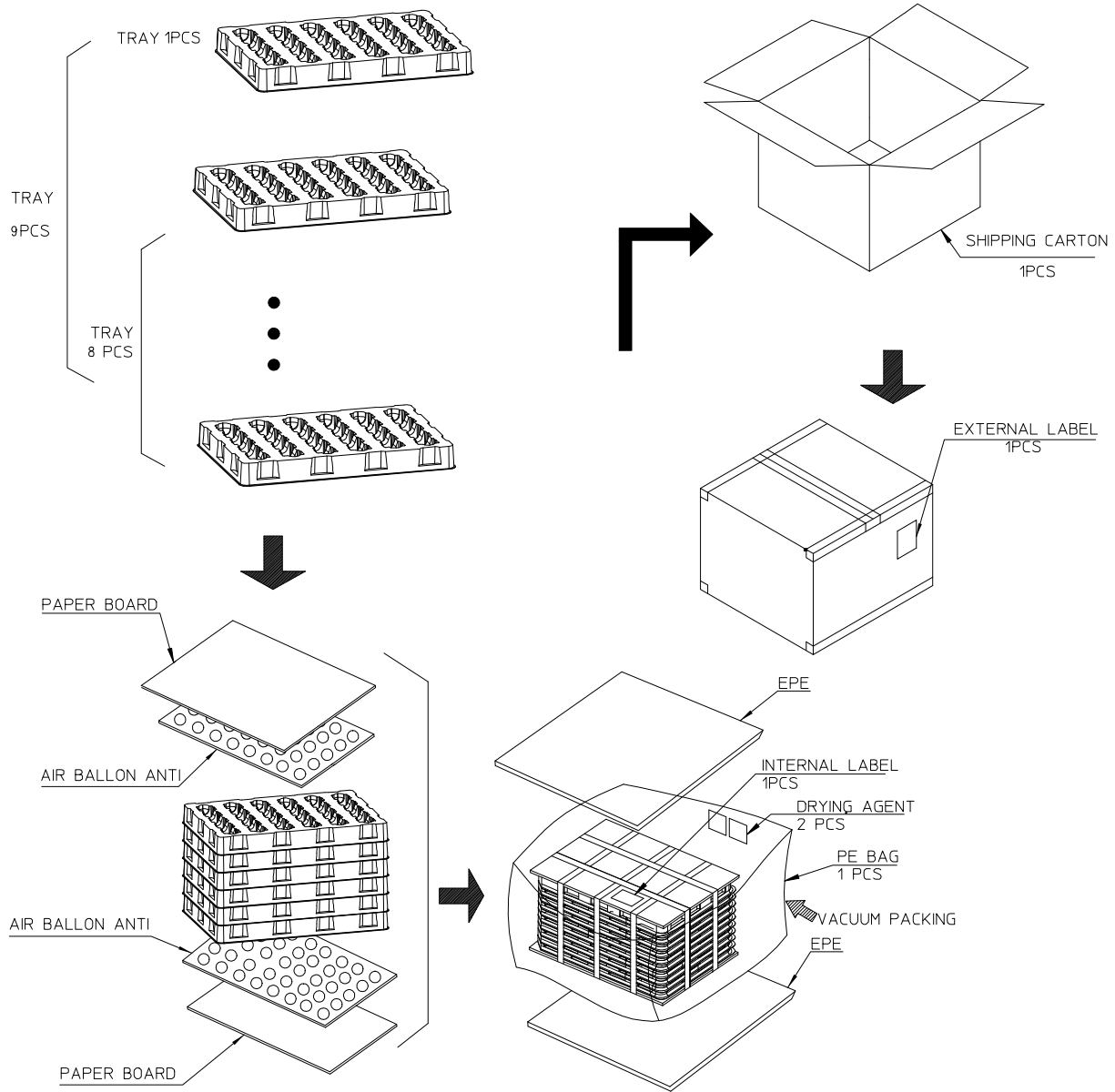
5.The Product Using Material And Processing Must Conform To The "WI-PZ-142"HSF Technical Standard Control Requirements.

6.P/N Order



REV.	REVISION RECORD	DATE		GENERAL TOLERANCES		SCALE 1:1	NAME	DATE	PART NO.	DWG NO.				
X0	FIRST RELEASE	2026.01.06		LINEAR	ANGLES	APPROVED	Jackie Tan	2026.04.22	19-01-000016	ENDE05				
X1	Update the structure according	2026.04.22		0.0±0.25	X° REF±6°	DESIGNER	Daniel Dong	2026.04.22	TITLE BOARD TO BOARD CONN 6.0&2.0&2P+20S+2P CIRCUTIS REC R/A DIP TYPE					
				UNIT: MM	0.00±0.15	X° ±3°								
				SIZE: A4	0.000±0.08	X° X' ±2°	DRAWN	Hu.CH	2026.04.22					
											REV	X1	SHEET	2/3

RoHS 2.0+HF



NOTES:
1. STAPLES SHOULD ONLY BE USED TO SET UP CART
ALL CARTON CLOSURES MUST BE DONE WITH TRA
2. FILL PACKAGING TRAY WITH THE QUANTITIES AS
INDICATED IN CHART.

PRODUCT NUMBER	PER TRAY	TOTAL TRAYS	PER CARTON	TRAY COLOR
19-01-000016	30 PCS	8PCS	240 PCS	BLACK

REV.	REVISION RECORD	DATE		GENERAL TOLERANCES		SCALE 1:1	NAME	DATE	PART NO.	DWG NO.				
X0	FIRST RELEASE	2026.01.06		LINEAR	ANGLES	APPROVED	Jackie Tan	2026.04.22	19-01-000016	ENDE05				
X1	Update the structure according	2026.04.22		0.0±0.25	X° REF±6°	DESIGNER	Daniel Dong	2026.04.22						
				UNIT: MM	0.00±0.15	X° ±3°	DRAWN	Hu.CH						
				SIZE: A4	0.000±0.08	X° X' ±2°				REV				

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